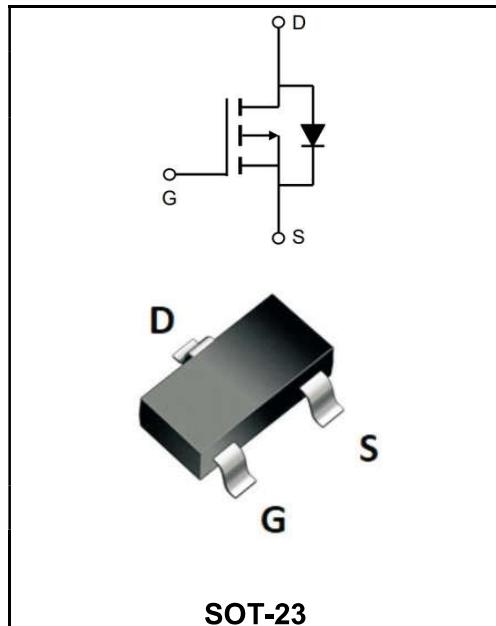


-40V P-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	-3A
V_{DSS}	-40V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 75mΩ (Type: 62 mΩ)


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW3P04A	SOT-23	3P04A	3000PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	-40	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ -4.5V^1$ @ $T_A=25^\circ\text{C}$	I_D	-3.7	A
Continuous Drain Current, $V_{GS} @ -4.5V^1$ @ $T_A=70^\circ\text{C}$	I_D	-3.0	A
Pulsed Drain Current ²	I_{DM}	-16.1	A
Total Power Dissipation ³ @ $T_A=25^\circ\text{C}$	P_D	1.32	W
Total Power Dissipation ³ @ $T_A=70^\circ\text{C}$	P_D	0.84	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	125	°C/W
Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	$R_{\theta JA}$	95	°C/W
Thermal Resistance Junction to Case ¹	$R_{\theta JC}$	80	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	BV _{DSS}	-40	-44	-	V
BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	ΔBV _{DSS/ΔTJ}	-	-0.018	-	V/°C
Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-3A	R _{DS(ON)}	-	62	75	mΩ
	V _{GS} =-4.5V, I _D =-2A		-	81	100	
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	V _{GS(th)}	-1.0	-1.5	-2.5	V
V _{GS(th)} Temperature Coefficient		ΔV _{GS(th)}	-	2.5	-	mV/°C
Drain-Source Leakage Current	V _{DS} =-40V , V _{GS} =0V , T _J =25°C	I _{DSS}	-	-	-1	μA
	V _{DS} =-40V , V _{GS} =0V , T _J =55°C		-	-	-5	
Gate –Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Forward Transconductance	V _{DS} =-5V , I _D =-3V	g _{fs}	-	5.8	-	S
Total Gate Charge(-4.5V)	V _{DS} =-32V V _{GS} =-4.5V I _D =-3A	Q _g	-	6.4	-	nC
Gate-Source Charge		Q _{gs}	-	2.1	-	
Gate-Drain Charge		Q _{gd}	-	2.5	-	
Turn-on delay time	V _{DD} =-20V V _{GS} =-4.5V I _D = -3A R _G =3.3Ω	t _{d(on)}	-	4.2	-	ns
Rise Time		T _r	-	23	-	
Turn-Off Delay Time		t _{d(OFF)}	-	26.8	-	
Fall Time		t _f	-	20.6	-	
Input Capacitance	V _{DS} =-15V V _{GS} =0V f=1MHz	C _{iss}	-	620	-	pF
Output Capacitance		C _{oss}	-	65	-	
Reverse Transfer Capacitance		C _{rss}	-	53	-	
Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current	I _s	-	-	-3.2	A
Pulsed Source Current ^{2,4}		I _{SM}	-	-	-16.1	A
Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C	V _{SD}	-	-	-1	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

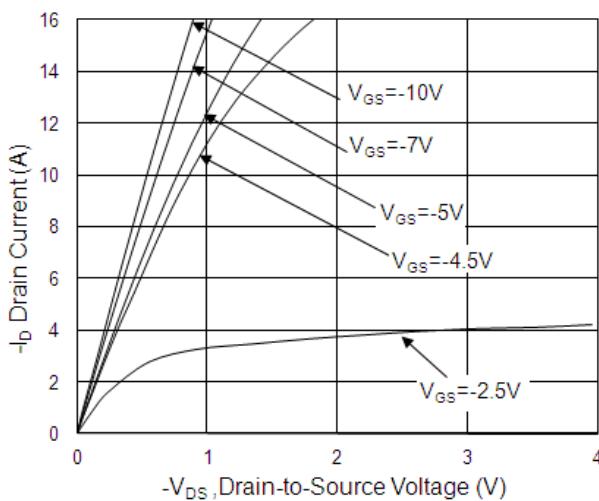


Fig.1 Typical Output Characteristics

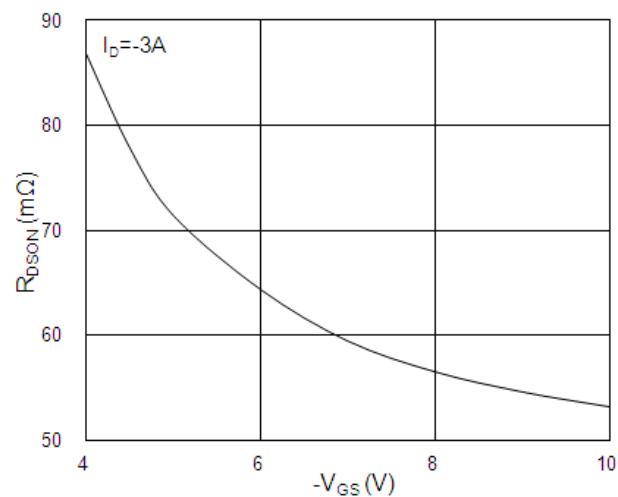


Fig.2 On-Resistance vs. G-S Voltage

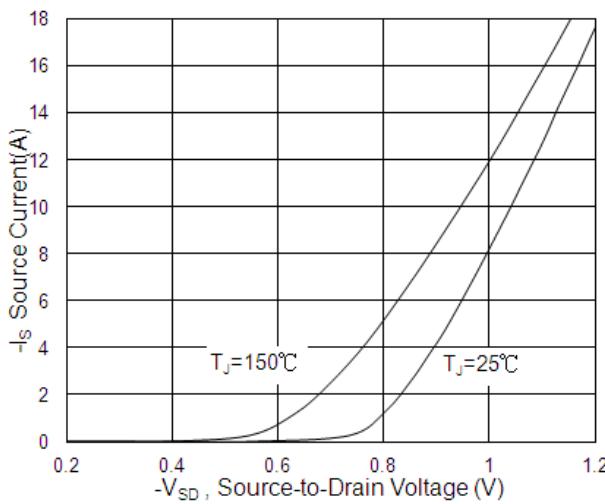


Fig.3 Forward Characteristics Of Reverse

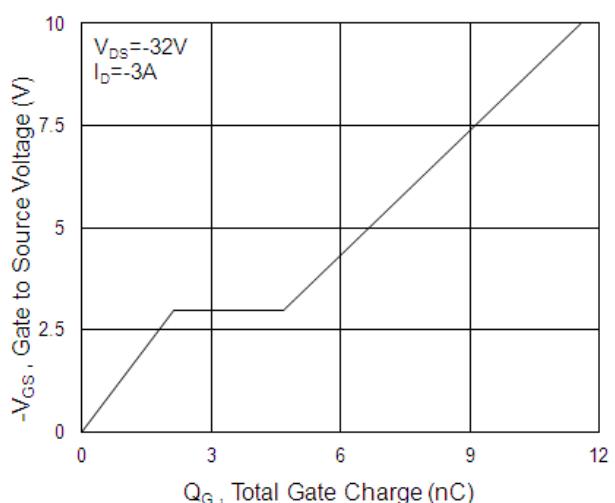


Fig.4 Gate-Charge Characteristics

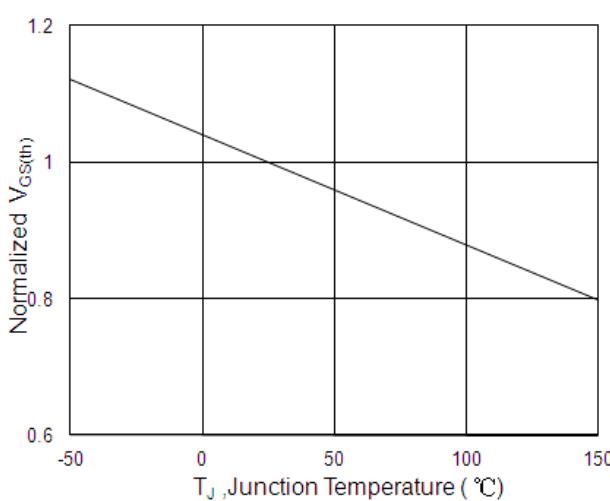


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

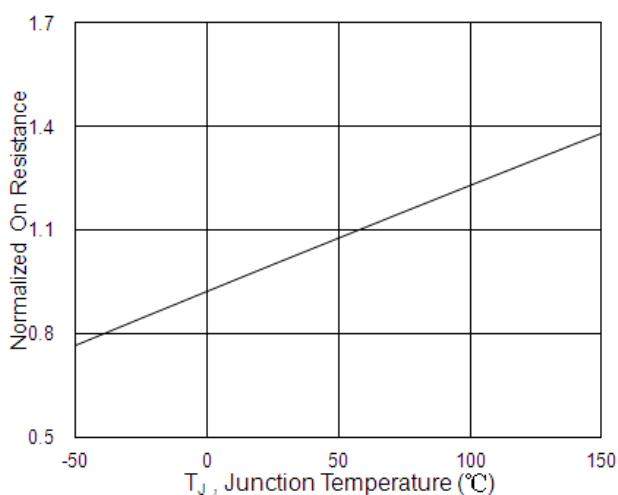


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Ratings and Characteristic Curves

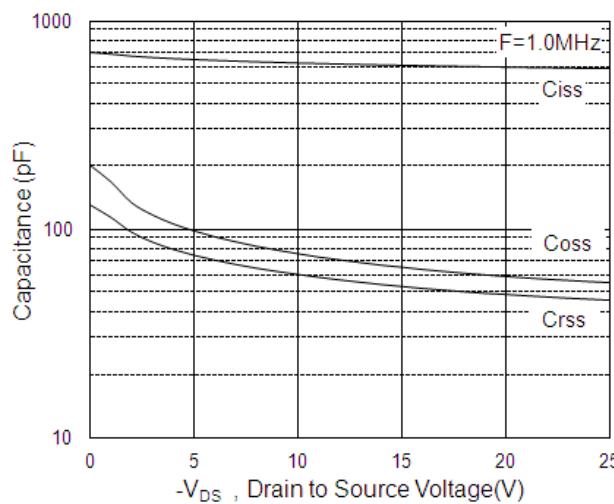


Fig.7 Capacitance

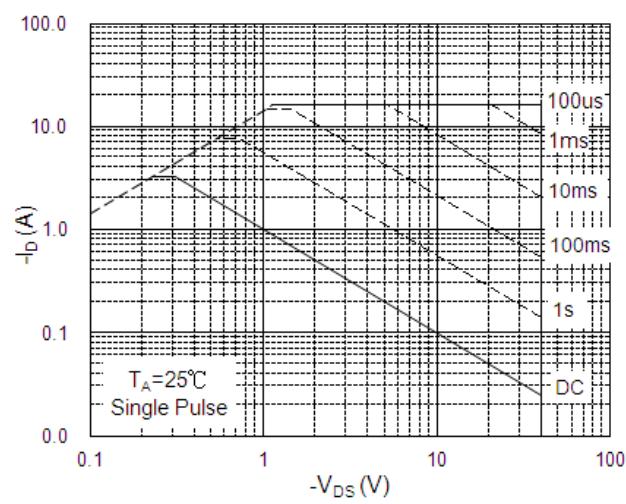


Fig.8 Safe Operating Area

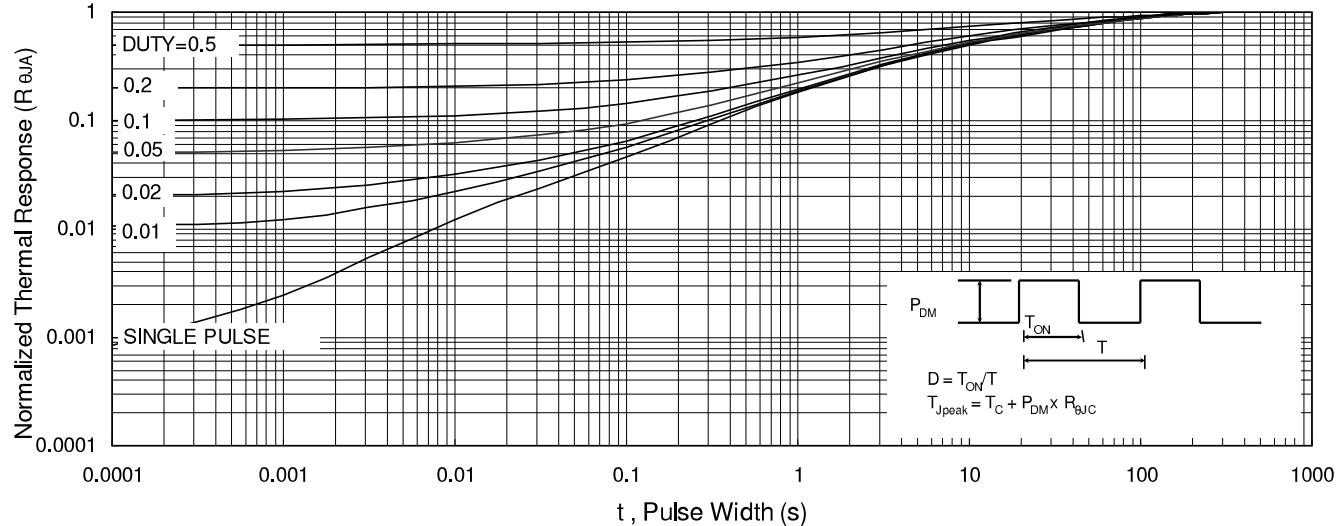


Fig.9 Normalized Maximum Transient Thermal Impedance

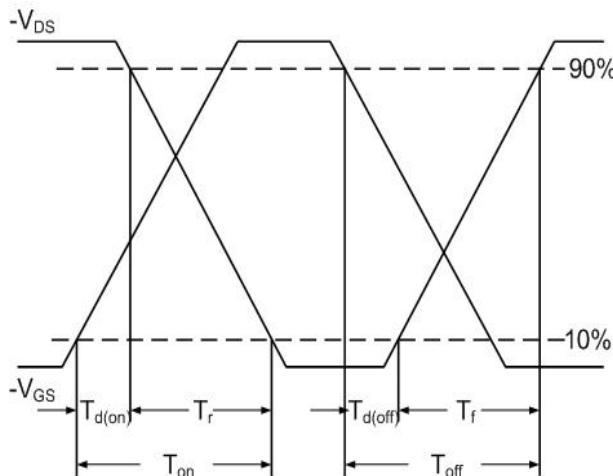


Fig.10 Switching Time Waveform

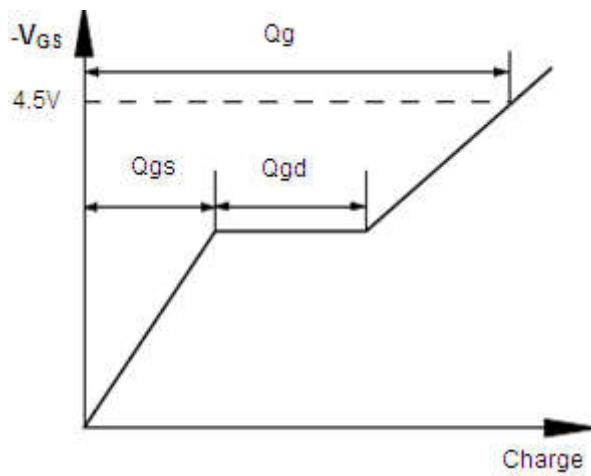
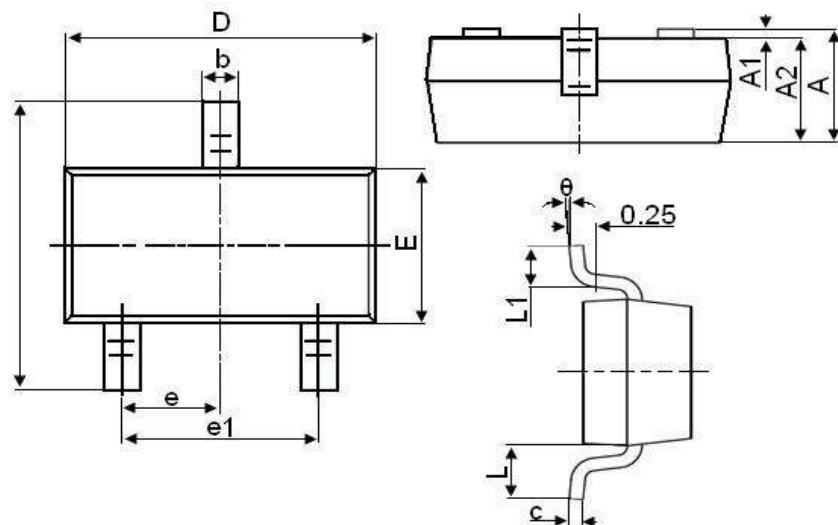


Fig.11 Gate Charge Waveform

Package Outline Dimensions Millimeters

SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°